

Claims

What is claimed is:

- 1 1. An electronic structure, comprising:
2 a substrate, wherein the substrate is divided into a plurality of segments, and
3 a semiconductor device electrically coupled to each of the segments.
- 1 2. The electronic structure of claim 1, wherein the semiconductor device is symmetrically coupled
2 to each segment.
- 1 3. The electronic structure of claim 1, wherein the semiconductor device is not symmetrically
2 coupled to each segment.
- 1 4. The electronic structure of claim 1, wherein a first segment and a second segment of the
2 plurality of segments are congruent with respect to each other.
- 1 5. The electronic structure of claim 1, wherein a first segment and a second segment of the
2 plurality of segments are not congruent with respect to each other.
- 1 6. The electronic structure of claim 1, wherein the plurality of segments are square segments.

1 7. The electronic structure of claim 1, wherein the plurality of segments consists of 4 segments.

1 8. The electronic structure of claim 1, wherein the substrate is a chip carrier, and wherein the
2 semiconductor device is a semiconductor chip.

1 9. An electronic structure, comprising:
2 a substrate; and
3 a semiconductor device electrically coupled to the substrate, wherein the semiconductor is
4 divided into a plurality of segments.

1 10. The electronic structure of claim 9, wherein the length of each segment of the semiconductor
2 device is greater than or equal to 5 millimeters.

1 11. The electronic structure of claim 9, wherein a first segment and a second segment of the
2 plurality of segments are congruent with respect to each other.

1 12. The electronic structure of claim 9, wherein a first segment and a second segment of the
2 plurality of segments are not congruent with respect to each other.

1 13. The electronic structure of claim 9, wherein the plurality of segments are square segments.

1 14. A method for forming an electronic structure, comprising:
2 dividing a substrate into a plurality of segments, and
3 electrically coupling a semiconductor device to each segment of the plurality of segments
4 of the substrate.

1 15. The method of claim 14, wherein the semiconductor device is symmetrically coupled to each
2 segment.

1 16. The method of claim 14, wherein the semiconductor device is not symmetrically coupled to
2 each segment.

1 17. The method of claim 14, wherein a first segment and a second segment of the plurality of
2 segments are congruent with respect to each other.

1 18. The method of claim 14, wherein a first segment and a second segment of the plurality of
2 segments are not congruent with respect to each other.

1 19. The method of claim 14, wherein the plurality of segments consists of 4 segments.

1 20. The method of claim 15, wherein the plurality of segments are square segments.